

UNIVERSITY OF CALIFORNIA, BERKELEY
College of Engineering
Department of Electrical Engineering and Computer Sciences

MIDTERM EXAMINATION

EE 130/230A: Spring 2014

Time allotted: 60 minutes

NAME: Solution

STUDENT ID#: _____

INSTRUCTIONS:

1. Unless otherwise stated, assume
 - a. temperature is 300 K
 - b. material is Si

2. **SHOW YOUR WORK.** (Make your methods clear to the grader!)
 - Specially, while using chart, make sure that you indicate how you have got your numbers. For example, if reading off mobility, clearly write down what doping density that corresponds to.
 - Clearly write down any assumption that you have made.
- **Clearly mark (underline or box) your answers.**
3. **Specify the units on answers whenever appropriate.**

SCORE: 1 _____ / 20

2 _____ / 20

Total _____ / 40

PHYSICAL CONSTANTS

Description	Symbol	Value
Electronic charge	q	1.6×10^{-19} C
Boltzmann's constant	k	8.62×10^{-5} eV/K
Thermal voltage at 300K	$V_T = \frac{kT}{q}$	0.026 V

PROPERTIES OF SILICON AT 300K

Description	Symbol	Value
Band gap energy	E_G	1.12 eV
Intrinsic carrier concentration	n_i	10^{10} cm ⁻³
Dielectric permittivity	ϵ_{Si}	1.0×10^{-12} F/cm

USEFUL NUMBERS

$$V_T \ln(10) = 0.060 \text{ V at } T=300\text{K}$$

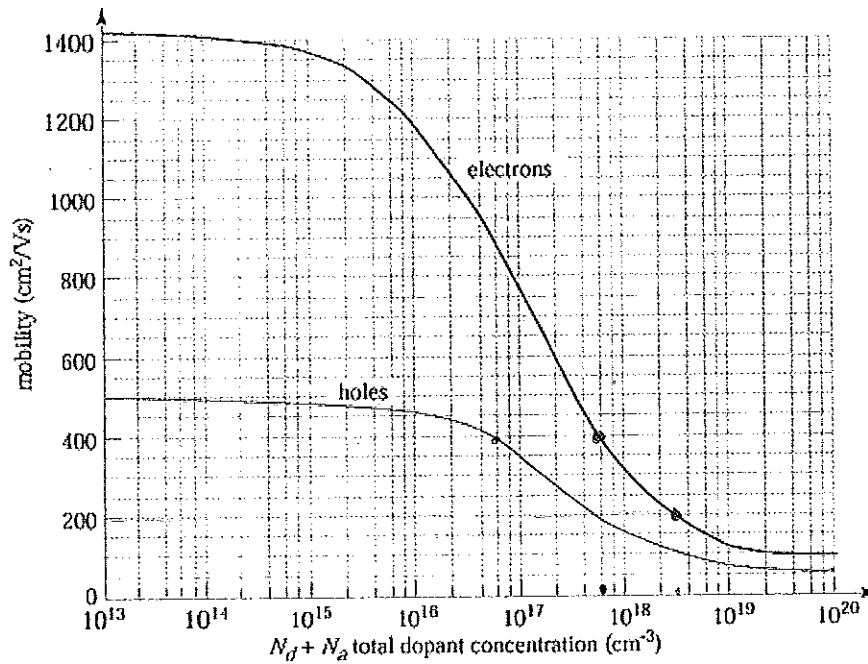
Depletion region Width:

$$W = \sqrt{\frac{2\epsilon}{q} \left(\frac{1}{N_a} + \frac{1}{N_d} \right) (V_{bi} - V_{Applied})}$$

Current in a PN junction:

$$I = A \left(\frac{D_p}{L_p} p_{n0} + \frac{D_n}{L_n} n_{p0} \right) (e^{qV_D/kT} - 1)$$

Electron and Hole Mobilities in Silicon at 300K



Prob 1 [20 pts].

(a) [4 pt] Assume that a Si sample has been doped with Ga (which is a group III element).

- (i) Will the electron density increase or decrease if one increases temperature? Why? [2pt]
- (ii) Will the hole density increase or decrease if one increases temperature? Why? [2pt]

Ga \rightarrow group III \rightarrow acceptor

(i) $n = \frac{n_i^2}{N_{Ga}}$, increases with T due to n_i

(ii) $p = N_{Ga}$; independent except for very high T where n_i is comparable to N_{Ga} .

(b) [6 pt] Assume that a Si sample of length 500 μm at $T=300^\circ\text{K}$ is uniformly doped with acceptors at a concentration of $2.5 \times 10^{17} \text{ cm}^{-3}$. Following that, the semiconductor is *compensated* such that the carrier mobility comes out to be $400 \text{ cm}^2/\text{v-sec}$. If 5V is applied across this sample, find out the current density.

$(N_A + N_d)$ for $400 \text{ cm}^2/\text{v-sec}$ can only be found for electrons above $2.5 \times 10^{17}/\text{cm}^3$ doping density.

$N_A + N_d = 6 \times 10^{17}/\text{cm}^3$ from the plot

$$\therefore N_d = (6 - 2.5) \times 10^{17} = 3.5 \times 10^{17}/\text{cm}^3$$

$$\therefore n = N_d - N_A = (3.5 - 2.5) \times 10^{17} = 10^{17}/\text{cm}^3$$

$$J = qn\mu_n E = 1.6 \times 10^{-19} \times 10^{17} \times \frac{5}{500 \times 10^{-4}} \times 400$$

$$J = 6.4 \times 10^2 \text{ A/cm}^2$$

(c) [6 pts] [20 pts] A sample of N type Si is kept at room temperature. When an electric field with a strength of 1000 V/cm is applied to the sample, the electron velocity is measured and found to be 2×10^5 cm/sec.

- (a) [10 pts] Estimate the thermal equilibrium electron and hole densities, indicating which is the minority carrier.
 (b) [10 pts] Find the position of E_F with respect to E_c and E_v .

$$(a) \quad v = \mu_n E = 2 \times 10^5 \text{ cm/sec}$$

$$\therefore \mu_n = \frac{2 \times 10^5}{1000} = 200 \text{ cm}^2/\text{v-sec}$$

From the plot, $N_d = 3 \times 10^{18} / \text{cm}^3$

majority	$n = 3 \times 10^{18} / \text{cm}^3$
minority	$p = \frac{10^{20}}{3 \times 10^{18}} = 33.33 / \text{cm}^3$

$$(b) \quad n = n_i e^{\frac{E_F - E_i}{kT}} ; E_F - E_i = kT \ln \frac{3 \times 10^{18}}{10^{10}} = 0.5055 \text{ eV}$$

$$E_c - E_i = E_g/2 = 1.1/2 = 0.55 \text{ eV}$$

$\therefore E_c - E_F = 0.55 - 0.5055 = 0.0445 \text{ eV}$
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$\therefore (E_F - E_v) = (E_c - E_v) + (E_F - E_c) = 1.1 - 0.0445 = 1.0555 \text{ eV}$

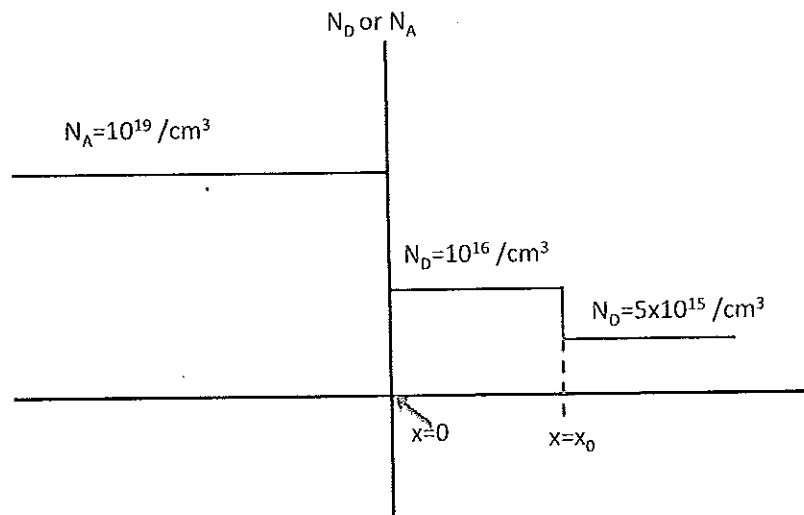
(d)[4 pts] Please indicate 'True' or 'False'

Phenomenon	True/False
Above room temperature, mobility is more dominantly affected by phonon scattering than impurity scattering	T
In Si, recombination happens mainly through band-to-band transition	F
When low level injection holds, $np=n_i^2$ also holds	F
Carrier lifetime will typically be smaller in intrinsic Si compared to doped Si	F

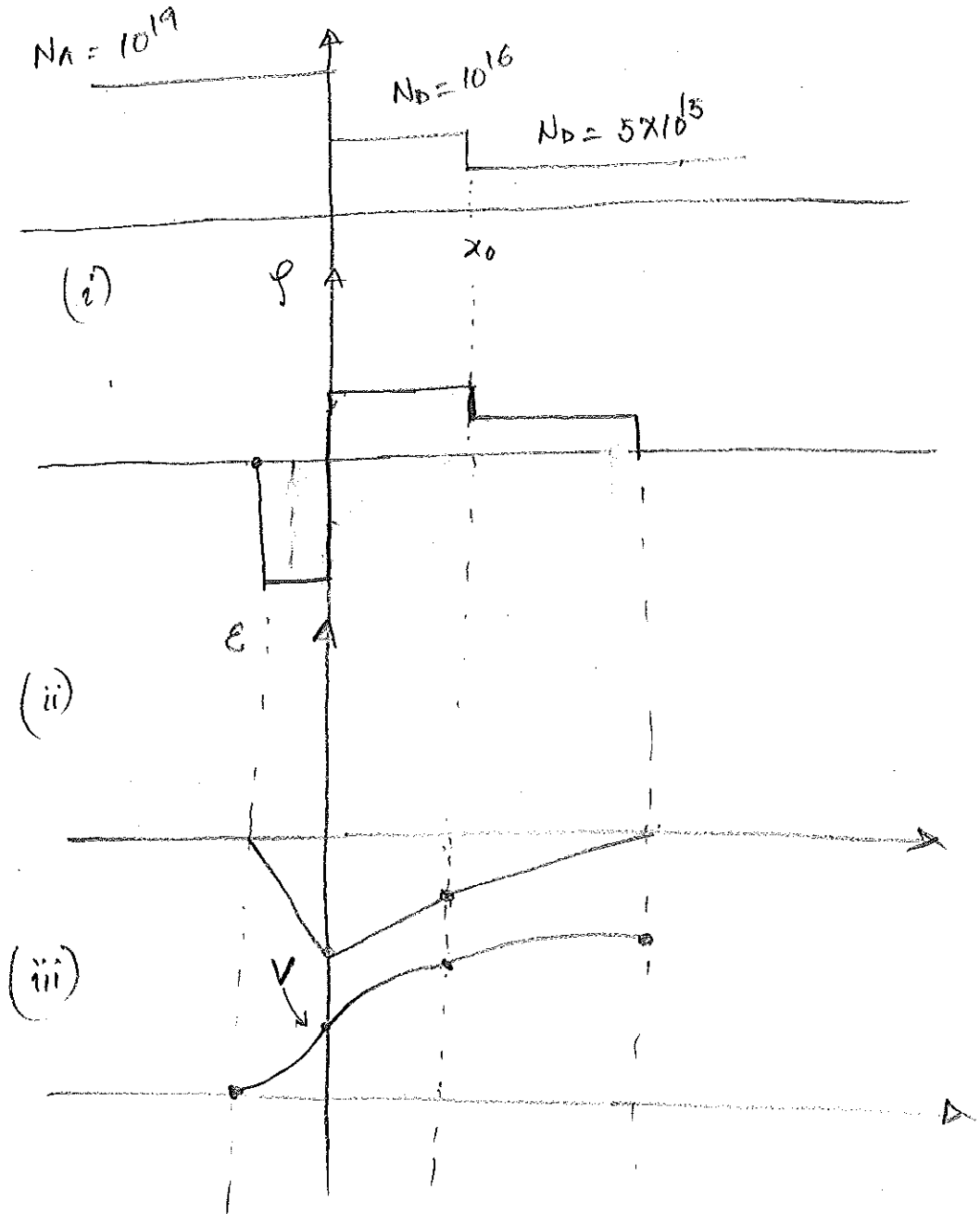
Prob 2: [20 pts] For the P-N junction diode shown below, answer the following questions. Note that the depletion width on the N-side, $x_n > x_0$. Ignore any discontinuity of electric field in the junctions. Note that the picture shown below only shows the amplitude (and not 'sign') of the doping concentrations.

While drawing the diagrams,

- please be careful to indicate *relative quantities* (such as the amplitude of charge densities, the curvature of potential profiles, the width of the depletion region etc)
- For each diagram you need to draw quantities at both the P and N sides
- If you are using the same diagram to answer multiple questions, please mark the answers clearly.



- (i) [1 pt] Draw the charge density profile
- (ii) [1 pt] Draw the Electric Field Profile
- (iii) [1 pt] Draw the Potential Profile
- (iv) [3 pt] Calculate the depletion region width
- (v) [2 pt] Calculate the Built in potential
- (vi) [2 pt] Calculate the maximum electric field
- (vii) [4 pt] Draw the current density profiles for both electrons and holes [Two profiles on each side and the total current] at a forward bias of 0.3V.
- (viii) [2 pt] Draw the Energy band diagram at the forward bias condition of (vi).
- (ix) [2 pt] Draw the profile of quasi Fermi levels of both electrons and holes.
- (x) [2 pt] Find the excess electron concentration at the edge of the depletion region at the N-side

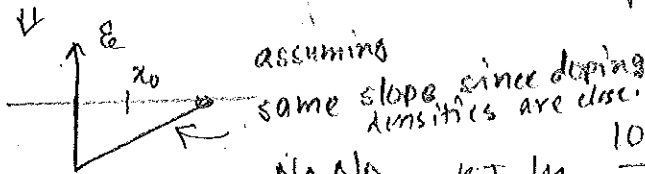


$$(iv) \frac{qN_D}{2\epsilon} x_0^2 + \frac{qN_D}{4\epsilon} (W-x_0)^2 = V_{bi} \quad [\text{Assuming } p^+n]$$

$$\therefore [2x_0^2 + (W-x_0)^2] = \frac{2\epsilon}{qN_D/2} V_{bi}$$

Assume, $W \gg x_0$ $W = \sqrt{\frac{2\epsilon}{qN_D/2} V_{bi}}$ $W \approx \sqrt{\frac{2\epsilon_s}{q} \frac{1}{N_D} V_{bi}} = \sqrt{\frac{2 \times 8.854 \times 10^{-14}}{1.6 \times 10^{19}} \frac{11.9}{5 \times 10^{15}}}$

$W = 4.7 \times 10^{-5} \text{ cm}$



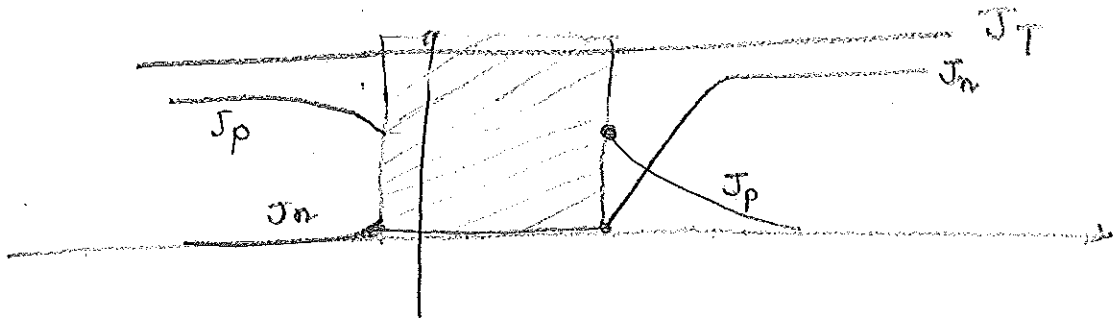
$$(v) V_{bi} = KT \ln \frac{N_A N_D}{n_i^2} = KT \ln \frac{10^{19} \times 10^{15} \times 5}{10^{20}} = 0.8766 \text{ V}$$

(vi) With the same approximations as in (iv)

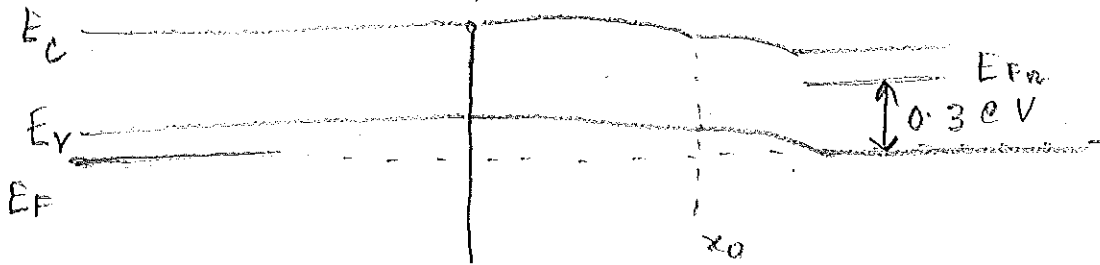
$$E = -\frac{qN_D}{\epsilon} (W-x)$$

$$\therefore E_{max} = \frac{qN_D/2 \cdot W}{\epsilon} = \frac{1.6 \times 10^{-19} \times 4.7 \times 10^{-5}}{11.9 \times 8.854 \times 10^{-14}} \times 5 \times 10^{15} = 3.63 \times 10^4 \text{ V/cm}$$

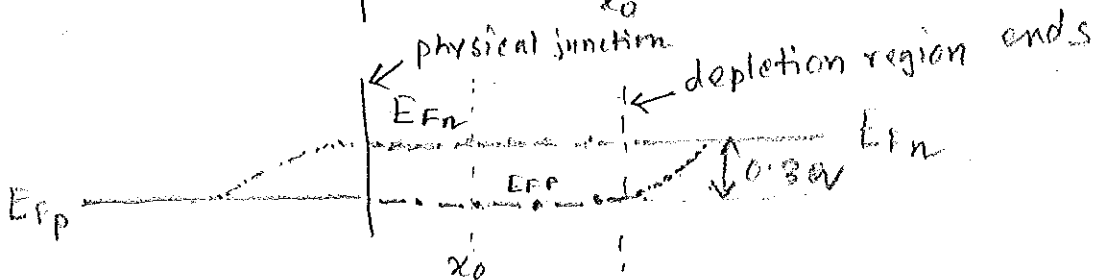
(vii)



(viii)



(ix)



$$(x) \Delta p = \frac{n_i^2}{N_D} \left(e^{\frac{0.3}{0.0259}} - 1 \right) = 2.195 \times 10^9 / \text{cm}^3$$